

L Number	Hits	Search Text	DB	Time stamp
1	0	bernstein-k\$,in.	USPAT; EPO; JPO; DERWENT	2004/06/11 13:29
2	108	bernstein-k\$.in.	USPAT; EPO; JPO; DERWENT	2004/06/11 13:56
3	761	LSSD or (level adj2 sensitive adj2 scan adj2 design)	USPAT; EPO; JPO; DERWENT	2004/06/11 13:57
4	0	(LSSD or (level adj2 sensitive adj2 scan adj2 design)) and bernstein-k\$.in.	USPAT; EPO; JPO; DERWENT	2004/06/11 13:57
5	45	(LSSD or (level adj2 sensitive adj2 scan adj2 design)) and (stress\$4 or burn-in or (reliablity adj2 test))	USPAT; EPO; JPO; DERWENT	2004/06/11 13:58
6	30	(LSSD or (level adj2 sensitive adj2 scan adj2 design)) and (stress\$4 or burn-in or (reliablity adj2 test)) and (VCC or VDD or voltage\$1 or (power adj2 rail\$1))	USPAT; EPO; JPO; DERWENT	2004/06/11 13:59
7	27	(LSSD or (level adj2 sensitive adj2 scan adj2 design)) and (stress\$4 or burn-in or (reliablity adj2 test)) and (VCC or VDD or voltage\$1 or (power adj2 rail\$1)) and (flip-flop\$1 or latch\$3)	USPAT; EPO; JPO; DERWENT	2004/06/11 14:00
8	27	(LSSD or (level adj2 sensitive adj2 scan adj2 design)) and (stress\$4 or burn-in or (reliablity adj2 test)) and (VCC or VDD or voltage\$1 or (power adj2 rail\$1)) and (flip-flop\$1 or latch\$3) and (logic or core or combinatorial)	USPAT; EPO; JPO; DERWENT	2004/06/11 14:00
9	27	(LSSD or (level adj2 sensitive adj2 scan adj2 design)) and (stress\$4 or burn-in or (reliablity adj2 test)) and (VCC\$1 or VDD\$1 or voltage\$1 or (power adj2 rail\$1)) and (flip-flop\$1 or latch\$3) and (logic or core or combinatorial)	USPAT; EPO; JPO; DERWENT	2004/06/11 14:01
10	36	(LSSD or (level adj2 sensitive adj2 scan adj2 design)) and (stress\$4 or burn-in or (reliablity adj2 test)) and (VCC\$1 or VDD\$1 or voltage\$1 or (power adj2 rail\$1) or de-power\$ or power\$4) and (flip-flop\$1 or latch\$3) and (logic or core or combinatorial)	USPAT; EPO; JPO; DERWENT	2004/06/11 14:02

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## 1 Analysis of grouped and censored data from step-stress life test

*Chengjie Xiong; Ming Ji;*

Reliability, IEEE Transactions on , Volume: 53 , Issue: 1 , March 2004

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## 2 Selection of display devices used at man-machine interfaces based on human factors

*Muraoka, T.; Ikeda, H.;*

Industrial Electronics, IEEE Transactions on , Volume: 51 , Issue: 2 , April 200

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## 3 Optical fiber stress-location measurement by synthesis of binary op coherence function

*Hotate, K.; Kuramoto, A.; Zuyuan He;*

Photonics Technology Letters, IEEE , Volume: 16 , Issue: 2 , Feb. 2004

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## 4 Polymer MEMS-based Fabry-Perot shear stress sensor

*Fan-Gang Tseng; Chun-Jun Lin;*

Sensors Journal, IEEE , Volume: 3 , Issue: 6 , Dec. 2003

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**5 Stress Relaxation and Fatigue of Two Electromechanical Spring Mate Strengthened by Thermomechanical Processing***Fox, A.;*

Parts, Materials and Packaging, IEEE Transactions on , Volume: 7 , Issue: 1 , 1971

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Parts, Materials and Packaging, IEEE Transactions on , Volume: 1 , Issue: 1 , 1965

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**Plastic Packages in High Humidity and Temperature Environments***Striny, K.; Schelling, A.;*

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